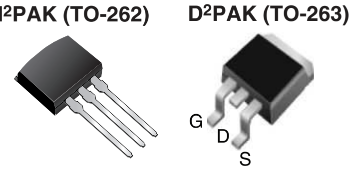
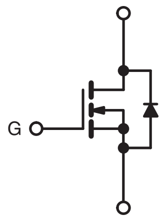
Power MOSFET

PRODUCT SUMMARY		
V_{DS} (V)	900	
$R_{DS(on)}$ (Ω)	V_{GS} = 10 V	8.0
Q_g (Max.) (nC)	38	
Q_{gs} (nC)	4.7	
Q_{gd} (nC)	21	
Configuration	Single	

I²PAK (TO-262) D²PAK (TO-263)





N-Channel MOSFET

FEATURES

- **Halogen-free According to IEC 61249-2-21 Definition**
- Surface Mount (IRFBF20S, SiHFBF20S)
- Low-Profile Through-Hole (IRFBF20L, SiHFBF20L)
- Available in Tape and Reel (IRFBF20S, SiHFBF20S)
- Dynamic dV/dt Rating
- 150 °C Operating Temperature
- Fast Switching
- Fully Avalanche Rated
- Compliant to RoHS Directive 2002/95/EC

RoHS* COMPLIANT
HALOGEN FREE Available

DESCRIPTION

Third generation Power MOSFETs form Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The D²PAK is a surface mount power package capabel of the accommodating die sizes up to HEX-4. It provides the highest power capability and the lowest possible on-resistance in any existing surface mount package. The D²PAK is suitable for high current applications because of its low internal connection resistance and can dissipate up to 2.0 W in a typical surface mount application. The through-hole version (IRFBF20L, SiHFBF20L) is available for low-profile applications.

ORDERING INFORMATION				
Package	D²PAK (TO-263)	D²PAK (TO-263)	D²PAK (TO-263)	I²PAK (TO-262)
Lead (Pb)-free and Halogen-free	SiHFBF20S-GE3	SiHFBF20STRL-GE3[a]	SiHFBF20STRR-GE3[a]	SiHFBF20L-GE3
Lead (Pb)-free	IRFBF20SPbF	IRFBF20STRLPbF[a]	IRFBF20STRRPbF[a]	IRFBF20LPbF
	SiHFBF20S-E3	SiHFBF20STL-E3[a]	SiHFBF20STR-E3[a]	SiHFBF20L-E3

Note

a. See device orientation.

ABSOLUTE MAXIMUM RATINGS (T_C = 25 °C, unless otherwise noted)					
PARAMETER			**SYMBOL**	**LIMIT**	**UNIT**
Drain-Source Voltage[e]			V_{DS}	900	V
Gate-Source Voltage[e]			V_{GS}	± 20	V
Continuous Drain Current	V_{GS} at 10 V	T_C = 25 °C	I_D	1.7	A
		T_C = 100 °C		1.1	
Pulsed Drain Current[a,e]			I_{DM}	6.8	
Linear Derating Factor				0.43	W/°C
Single Pulse Avalanche Energy[b, e]			E_{AS}	180	mJ
Repetitive Avalanche Current[a]			I_{AR}	1.7	A
Repetitive Avalanche Energy[a]			E_{AR}	5.4	mJ
Maximum Power Dissipation	T_C = 25 °C		P_D	54	W
	T_A = 25 °C			3.1	
Peak Diode Recovery dV/dt[c, e]			dV/dt	1.5	V/ns
Operating Junction and Storage Temperature Range			T_J, T_{stg}	- 55 to + 150	°C
Soldering Recommendations (Peak Temperature)	for 10 s			300[d]	
Mounting Torque	6-32 or M3 screw			10	N

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
b. V_{DD} = 50 V; starting T_J = 25 °C, L = 117 mH, R_g = 25 Ω, I_{AS} = 1.7 A (see fig. 12).
c. I_{SD} ≤ 1.7 A, dI/dt ≤ 70 A/μs, V_{DD} ≤ V_{DS}, T_J ≤ 150 °C.
d. 1.6 mm from case.
e. Uses IRFBF20, SiHFBF20 data and test conditions.

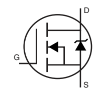
* Pb containing terminations are not RoHS compliant, exemptions may apply

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient (PCB Mounted, steady-state)[a]	R_{thJA}	-	40	°C/W
Maximum Junction-to-Case	R_{thJC}	-	2.3	

Note

a. When mounted on 1" square PCB (FR-4 or G-10 material).

SPECIFICATIONS (T_J = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V_{DS}	V_{GS} = 0, I_D = 250 μA		900	-	-	V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to 25 °C, I_D = 1 mA		-	1.1	-	mV/°C
Gate-Source Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 μA		2.0	-	4.0	V
Gate-Source Leakage	I_{GSS}	V_{GS} = ± 20 V		-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 900 V, V_{GS} = 0 V		-	-	100	μA
		V_{DS} = 720 V, V_{GS} = 0 V, T_J = 125 °C		-	-	500	
Drain-Source On-State Resistance	$R_{DS(on)}$	V_{GS} = 10 V	I_D = 1.0 A[b]	-	-	8.0	Ω
Forward Transconductance	g_{fs}	V_{DS} = 50 V, I_D = 1.0 A[b]		0.6	-	-	S
Dynamic							
Input Capacitance	C_{iss}	V_{GS} = 0 V, V_{DS} = 25 V, f = 1.0 MHz, see fig. 5		-	490	-	pF
Output Capacitance	C_{oss}			-	55	-	
Reverse Transfer Capacitance	C_{rss}			-	18	-	
Total Gate Charge	Q_g	V_{GS} = 10 V	I_D = 1.7 A, V_{DS} = 360 V, see fig. 6 and 13[b]	-	-	38	nC
Gate-Source Charge	Q_{gs}			-	-	4.7	
Gate-Drain Charge	Q_{gd}			-	-	21	
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = 450 V, I_D = 1.7 A, R_g = 18 Ω, V_{GS} = 10 V, see fig. 10[b]		-	8.0	-	ns
Rise Time	t_r			-	21	-	
Turn-Off Delay Time	$t_{d(off)}$			-	56	-	
Fall Time	t_f			-	32	-	

SPECIFICATIONS (T_J = 25 °C, unless otherwise noted)						
PARAMETER	**SYMBOL**	**TEST CONDITIONS**	**MIN.**	**TYP.**	**MAX.**	**UNIT**
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p - n junction diode 	-	-	1.7	A
Pulsed Diode Forward Current[a]	I_{SM}		-	-	6.8	
Body Diode Voltage	V_{SD}	T_J = 25 °C, I_S = 1.7 A, V_{GS} = 0 V[b]	-	-	1.5	V
Body Diode Reverse Recovery Time	t_{rr}	T_J = 25 °C, I_F = 1.7 A, dI/dt = 100 A/μs[b]	-	350	530	ns
Body Diode Reverse Recovery Charge	Q_{rr}		-	0.85	1.3	μC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)				

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
b. Pulse width ≤ 300 μs; duty cycle ≤ 2 %.
c. Uses IRFBF20/SiHFBF20 data and test conditions.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

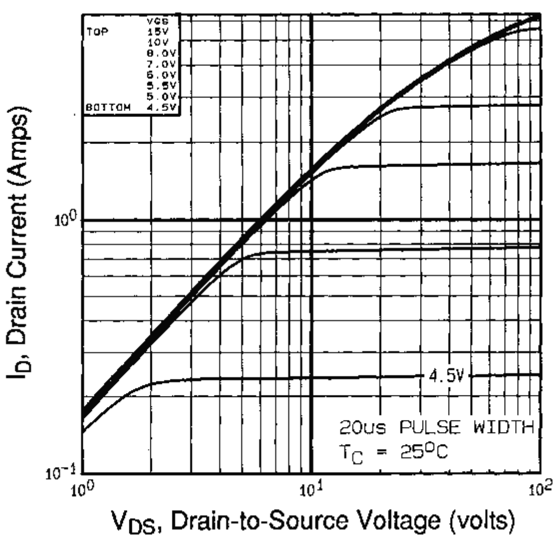


Fig. 1 - Typical Output Characteristics

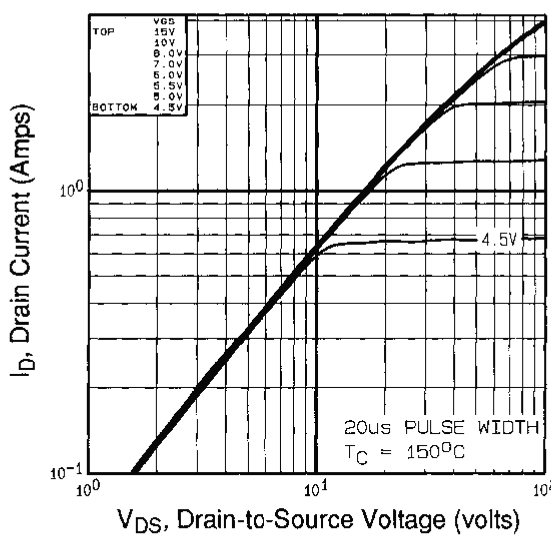


Fig. 2 - Typical Output Characteristics

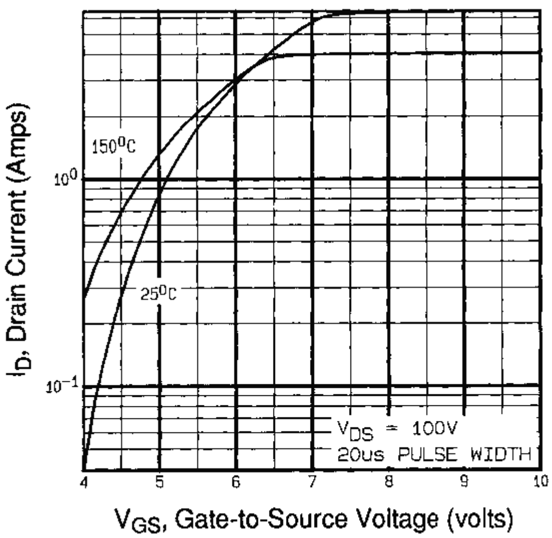


Fig. 3 - Typical Transfer Characteristics

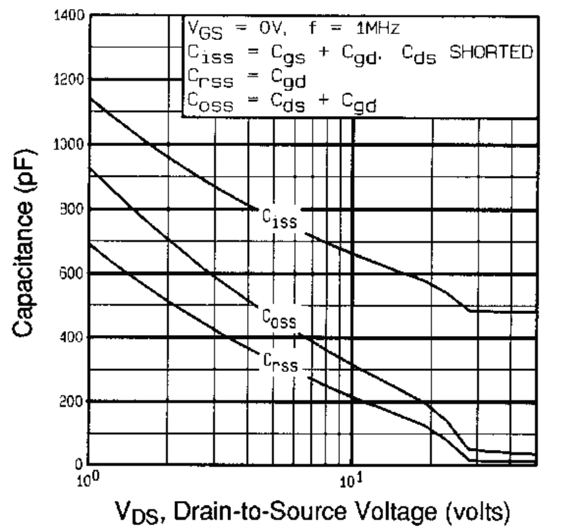


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

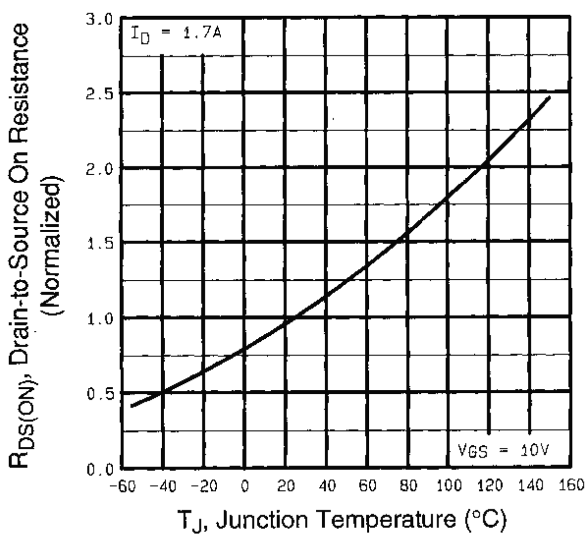


Fig. 4 - Normalized On-Resistance vs. Temperature

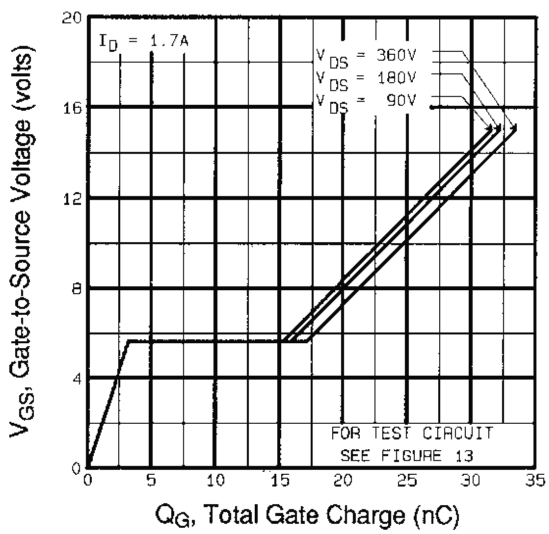


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

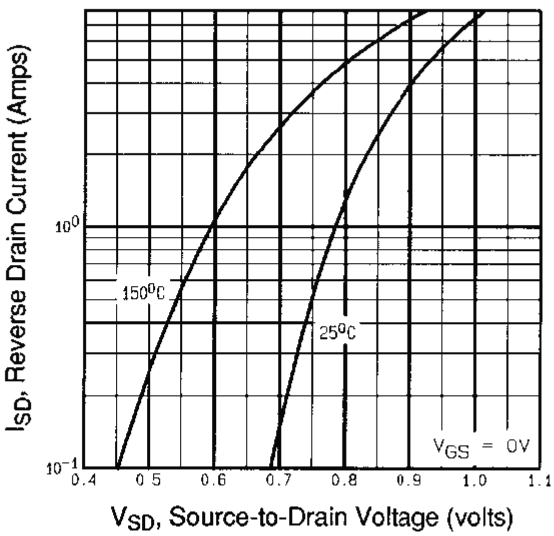


Fig. 7 - Typical Source-Drain Diode Forward Voltage

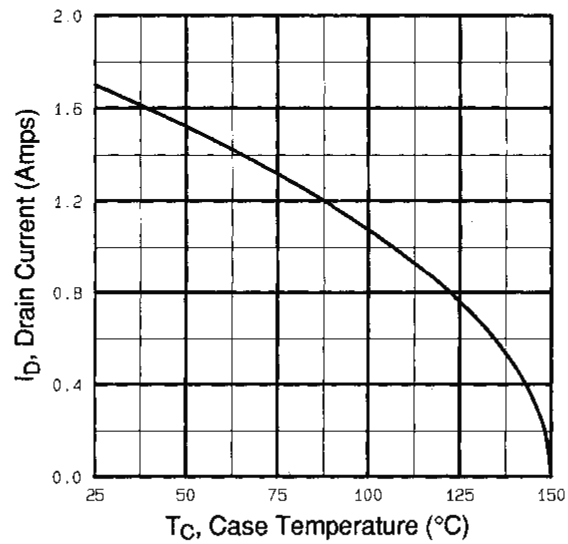


Fig. 9 - Maximum Drain Current vs. Case Temperature

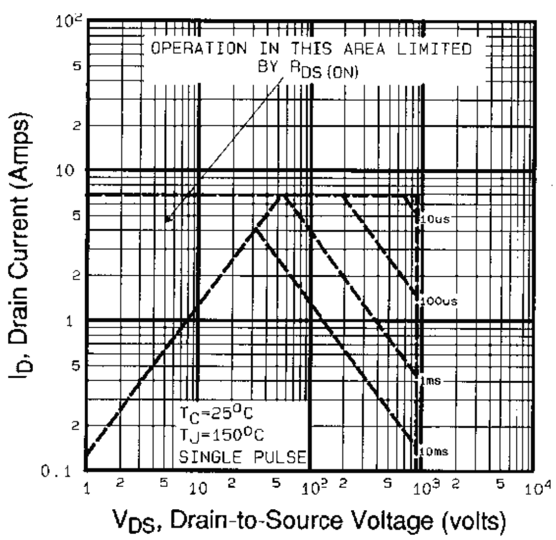


Fig. 8 - Maximum Safe Operating Area

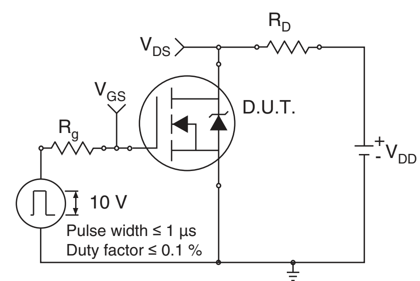


Fig. 10a - Switching Time Test Circuit

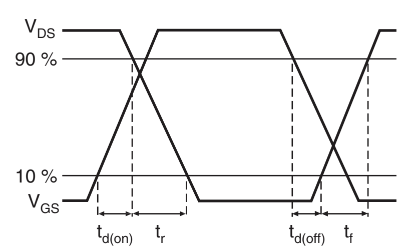


Fig. 10b - Switching Time Waveforms

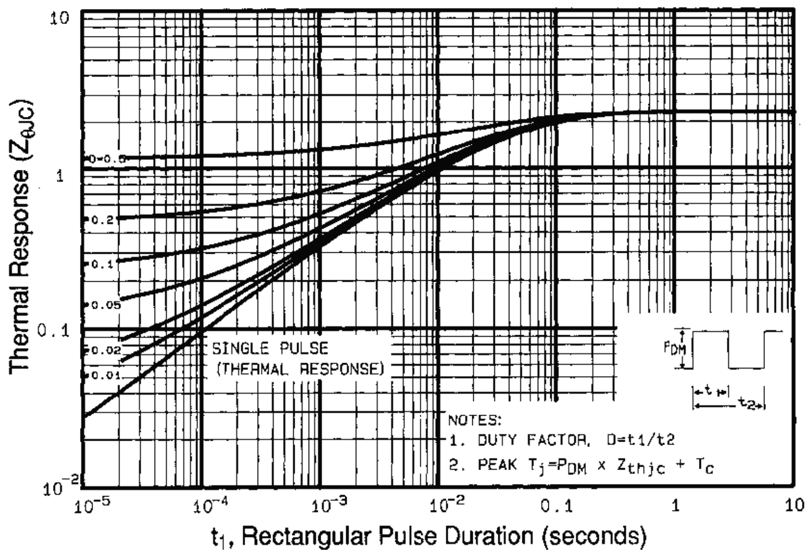


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

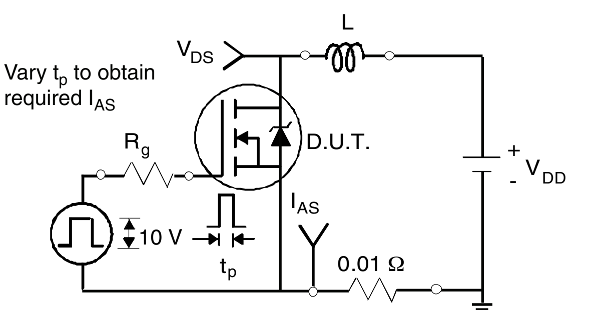


Fig. 12a - Unclamped Inductive Test Circuit

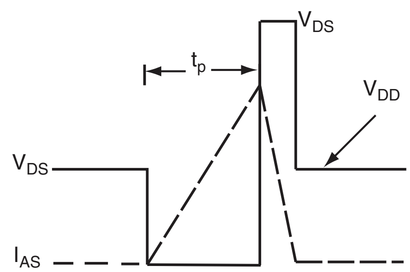


Fig. 12b - Unclamped Inductive Waveforms

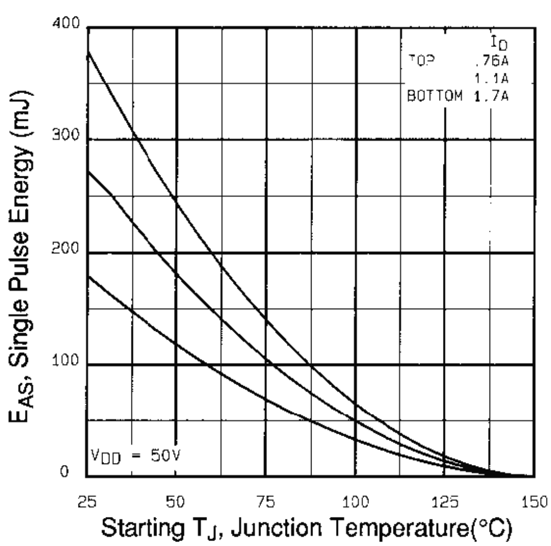


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

Document Number: 91121
S11-1053-Rev. B, 30-May-11

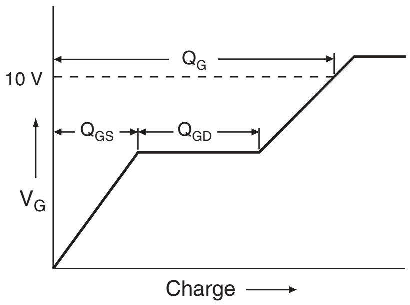


Fig. 13a - Basic Gate Charge Waveform

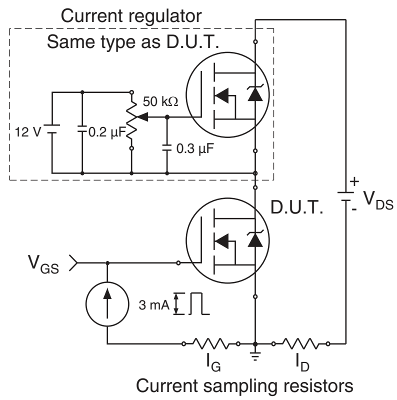
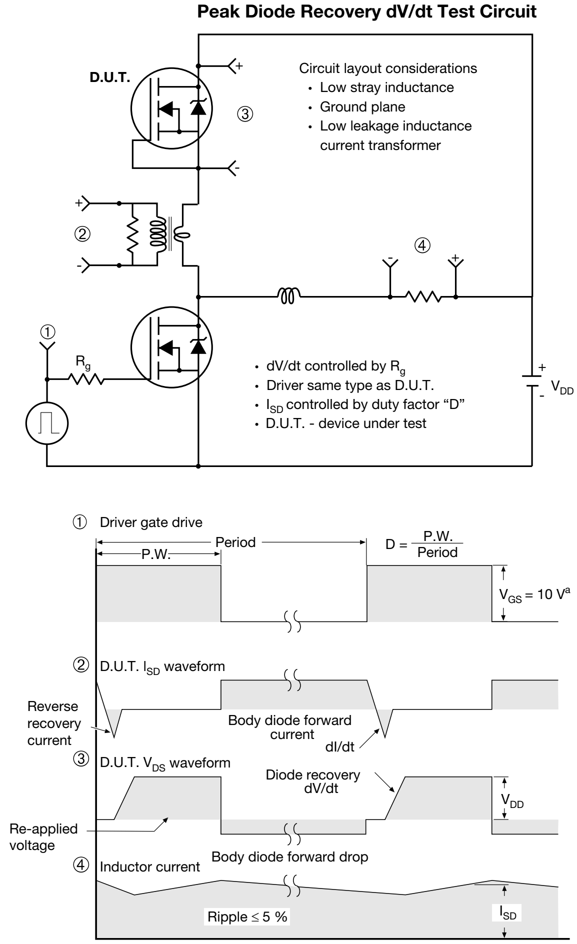


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



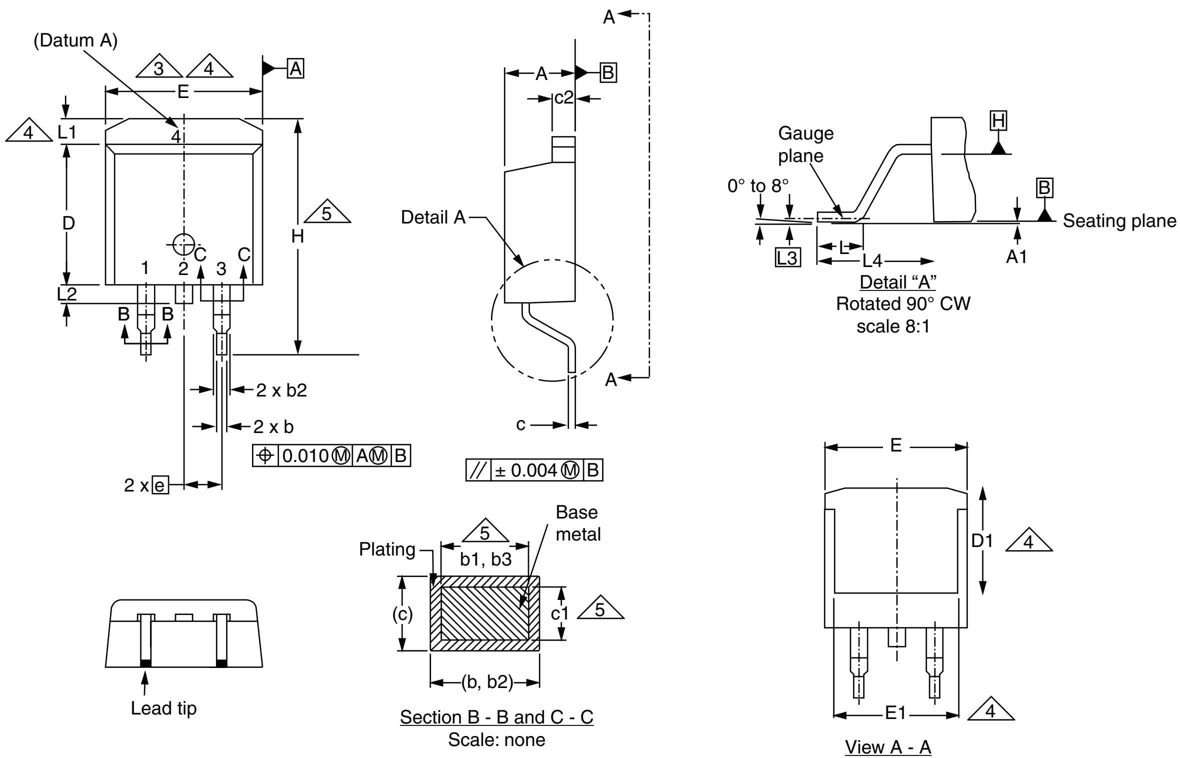
Note

a. V_{GS} = 5 V for logic level devices

Fig. 14 - For N-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?91121.

TO-263AB (HIGH VOLTAGE)



	MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.
A	4.06	4.83	0.160	0.190
A1	0.00	0.25	0.000	0.010
b	0.51	0.99	0.020	0.039
b1	0.51	0.89	0.020	0.035
b2	1.14	1.78	0.045	0.070
b3	1.14	1.73	0.045	0.068
c	0.38	0.74	0.015	0.029
c1	0.38	0.58	0.015	0.023
c2	1.14	1.65	0.045	0.065
D	8.38	9.65	0.330	0.380

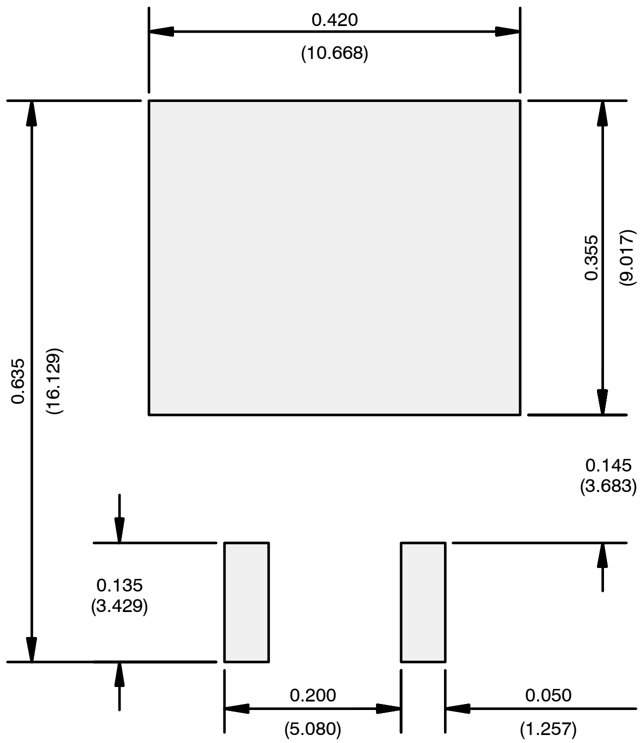
	MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.
D1	6.86	-	0.270	-
E	9.65	10.67	0.380	0.420
E1	6.22	-	0.245	-
e	2.54 BSC		0.100 BSC	
H	14.61	15.88	0.575	0.625
L	1.78	2.79	0.070	0.110
L1	-	1.65	-	0.066
L2	-	1.78	-	0.070
L3	0.25 BSC		0.010 BSC	
L4	4.78	5.28	0.188	0.208

ECN: S-82110-Rev. A, 15-Sep-08
DWG: 5970

Notes

1. Dimensioning and tolerancing per ASME Y14.5M-1994.
2. Dimensions are shown in millimeters (inches).
3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body at datum A.
4. Thermal PAD contour optional within dimension E, L1, D1 and E1.
5. Dimension b1 and c1 apply to base metal only.
6. Datum A and B to be determined at datum plane H.
7. Outline conforms to JEDEC outline to TO-263AB.

RECOMMENDED MINIMUM PADS FOR D^{2}PAK: 3-Lead



Recommended Minimum Pads
Dimensions in Inches/(mm)

Return to Index

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